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INFORMATION DISCLOSURE CITATION FORM FOR PATENT APPLICATION (FORM PTO-1449) (Substitute)		Docket No.: YOR920030196US1		Serial No.: 10/700,327		
		Applicant(s): Paul S. ANDRY et al.				
		Filing Date: 11/03/03		Group:		
U.S. PATENTS						
Initials	Patent Number	Issue Date	Name	Class	Sub-class	Filing date
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FOREIGN PATENT DOCUMENTS						
Initials	Document Number	Date	Country	Name		Translation? Yes/No/n/a
OTHER DOCUMENTS (Title, Author, Date, Pages, Etc., if known)						
	"Filling the via hole of IC by VPES (Vacuum Printing Encapsulation Systems for stacked chip (3D Packaging), A. Okuno et al., 2002 Electronics Components and Technology Conference					
Examiner's Signature:				Date Considered:		
Initial if reference was considered, whether or not citation is in conformance with MPEP. Mark through citation if not considered. Include a copy of this citation form with your next correspondence to the Applicant(s).						